

IN THE CLAIMS

Please **amend** claims 6 and 11 and **cancel** claims 17-29 and claims 39-47 without prejudice as shown in the Status of the Claims section, infra.

No new matter has been added. Additions are underlined and deletions are struckthrough.

STATUS OF THE CLAIMS

Claim 1 (Original). A solid state imaging device comprising:

a solid state image pickup device having an effective pixel region in one surface thereof;

a light-transparent cover arranged opposite to said effective pixel region and having planar dimensions smaller than those of said solid state image pickup device; and

an adhering section for adhering said solid state image pickup device and said light-transparent cover.

Claim 2 (Original). A solid state imaging device according to Claim 1, wherein said adhering section contains photosensitive adhesive.

Claim 3 (Original). A solid state imaging device according to Claim 2, wherein a space is formed between said effective pixel region and said light-transparent cover, and wherein said adhering section is formed outside said effective pixel region in said one surface of said solid state image pickup device.

Claim 4 (Original). A solid state imaging device according to Claim 3, wherein said adhering section seals the outer periphery of said space.

Claim 5 (Original). A solid state imaging device according to Claim 1, wherein a space is formed between said effective pixel region and said light-transparent cover, and wherein said adhering section is formed outside said effective pixel region in said one surface of said solid state image pickup device.

Claim 6 (currently amended). A semiconductor wafer on which a plurality of solid state image pickup devices each having an effective pixel region in one surface thereof are formed, comprising:

a light-transparent plate arranged opposite to said effective pixel region and  
having planar dimensions smaller than those of said solid state image pickup device;  
and

an adhering section for adhering said solid state image pickup device and said  
light-transparent plate.

Claim 7 (Original). A semiconductor wafer according to Claim 6, wherein said light-transparent plate is divided so as to form light-transparent covers each having planar dimensions smaller than those of said solid state image pickup device.

Claim 8 (Original). A semiconductor wafer according to Claim 7, wherein said adhering section contains photosensitive adhesive.

Claim 9 (Original). A semiconductor wafer according to Claim 7, wherein a space is formed between said effective pixel region and said light-transparent cover, and wherein said adhering section is formed outside said effective pixel region in said one surface of said solid state image pickup device.

Claim 10 (Original). A semiconductor wafer according to Claim 6, wherein said adhering section contains photosensitive adhesive.

Claim 11 (currently amended). A semiconductor wafer on which a plurality of solid state image pickup devices each having an effective pixel region in one surface thereof are formed, comprising:

a light-transparent cover arranged opposite to said effective pixel region and  
having planar dimensions smaller than those of said solid state image pickup device;  
and

an adhering section for adhering said solid state image pickup device and said light-transparent cover.

Claim 12 (Original). A semiconductor wafer according to Claim 11, wherein said adhering section contains photosensitive adhesive.

Claim 13 (Original). A semiconductor wafer according to Claim 12, wherein a space is formed between said effective pixel region and said light-transparent cover, and wherein said adhering section is formed outside said effective pixel region in said one surface of said solid state image pickup device.

Claim 14 (Original). A semiconductor wafer according to Claim 13, wherein said adhering section seals the outer periphery of said space.

Claim 15 (Original). A semiconductor wafer according to Claim 11, wherein a space is formed between said effective pixel region and said light-transparent cover, and wherein said adhering section is formed outside said effective pixel region in said one surface of said solid state image pickup device.

Claim 16 (Original). An optical device module comprising: a lens; a lens retainer for retaining said lens; and a solid state imaging device; wherein  
said solid state imaging device comprises:

a solid state image pickup device having an effective pixel region in one surface thereof;

a light-transparent cover arranged opposite to said effective pixel region and having planar dimensions smaller than those of said solid state image pickup device; and

an adhering section for adhering said solid state image pickup device and said light-transparent cover; and wherein

said light-transparent cover is arranged opposite to said lens and inside said lens retainer.

Claims 17-29 (canceled).

Claim 30 (Original). An optical device module comprising:  
a wiring board on which wiring is formed;

an image processor adhered to said wiring board and electrically connected to said wiring;

a solid state imaging device in which a light-transparent cover having planar dimensions smaller than those of a solid state image pickup device is attached opposite to the effective pixel region of said solid state image pickup device, and which is adhered to said image processor and electrically connected to said wiring; and

an optical path defining unit arranged opposite to said solid state imaging device and defining an optical path to said solid state imaging device.

**Claim 31 (Original).** An optical device module according to Claim 30, wherein said optical path defining unit retains a lens arranged opposite to said light-transparent cover of said solid state imaging device.

**Claim 32 (Original).** An optical device module comprising:

a solid state imaging module component formed by resin-sealing: a module component wiring board on which wiring is formed; an image processor adhered to said module component wiring board and electrically connected to said wiring; and a solid state imaging device in which a light-transparent cover having planar dimensions smaller than those of a solid state image pickup device is attached opposite to the effective pixel region of said solid state image pickup device, and which is adhered to said image processor and electrically connected to said wiring; in a state that the surface of said light-transparent cover is exposed; and

an optical path defining unit arranged opposite to said solid state imaging device and defining an optical path to said solid state imaging device.

**Claim 33 (Original).** An optical device module according to Claim 32, wherein an external terminal connected to said wiring is formed on the surface of said module component wiring board reverse to the surface to which said image processor is adhered.

**Claim 34 (Original).** An optical device module according to Claim 33, wherein said external terminal has a protruding shape.

Claim 35 (Original). An optical device module according to Claim 33, wherein said optical device module further comprises a wiring board on which wiring is formed, and wherein said external terminal of said module component wiring board is connected to said wiring of said wiring board.

Claim 36 (Original). An optical device module according to Claim 32, wherein said optical path defining unit retains a lens arranged opposite to said light-transparent cover of said solid state imaging device.

Claim 37 (Original). An optical device module comprising:

a wiring board on which wiring is formed;

an image processor adhered to said wiring board and electrically connected to said wiring;

a solid state imaging device in which a light-transparent cover having planar dimensions smaller than those of a solid state image pickup device is attached opposite to the effective pixel region of said solid state image pickup device, and which is adhered to said image processor and electrically connected to said wiring;

a sealing section for resin-sealing said wiring board, said image processor, and said solid state imaging device in a state that the surface of said light-transparent cover is exposed; and

an optical path defining unit arranged opposite to said solid state imaging device and defining an optical path to said solid state imaging device.

Claim 38 (Original). An optical device module according to Claim 37, wherein said optical path defining unit retains a lens arranged opposite to said light-transparent cover of said solid state imaging device.

Claims 39 – 47 (canceled).